



Characterizing the Nanoscribe Photonic GT System for Fabricating MEMS Bistable Structures

Kevin Tobin^{1,2}, Dilan Ratnayake², Kevin Walsh²

¹Mechanical Engineering, Lipscomb University

²Electrical and Computer Engineering, University of Louisville

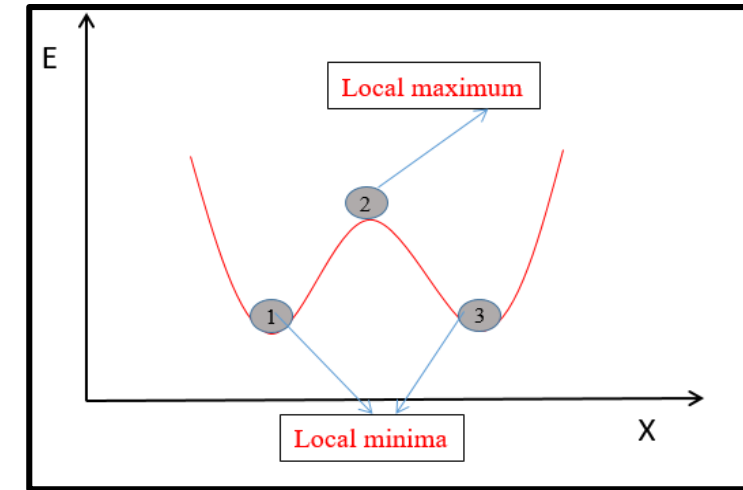


Outline

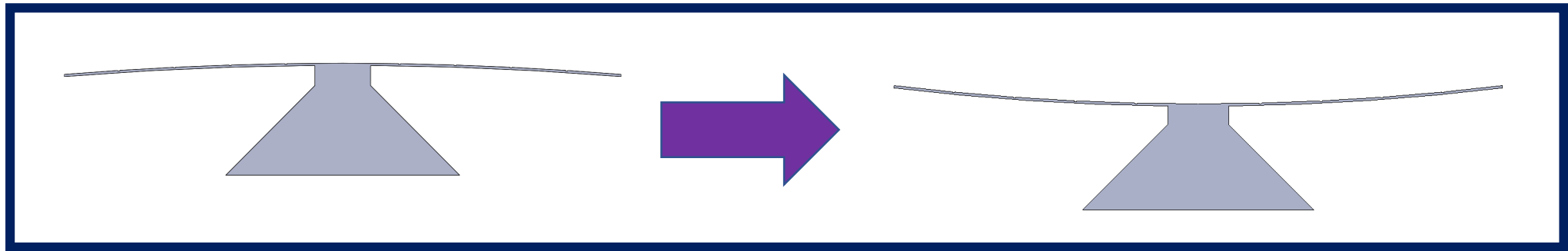
- Introduction
- Objective
- Fabrication Process and Materials
- Results
- Conclusions
- Recommendations

Introduction

- What is a “Bistable MEMS” device?
 - A MEMS device that is capable of transitioning into 2 distinct mechanical states
- Has the potential to be used in no electrical power (NEP) sensor and memory applications
- Previously required rather complex processing to fabricate, such as grayscale lithography, thermal reflow, or engineered stress in released micro-structures



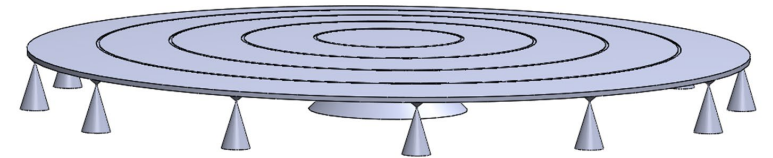
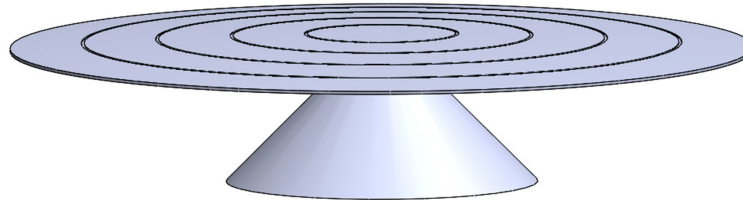
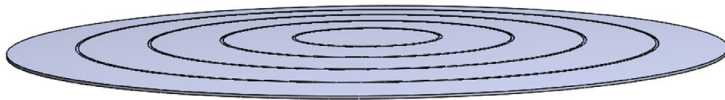
Bistability => has two equilibrium states



**What if there was a faster and more
flexible method for fabricating
Bistable MEMS structures?**

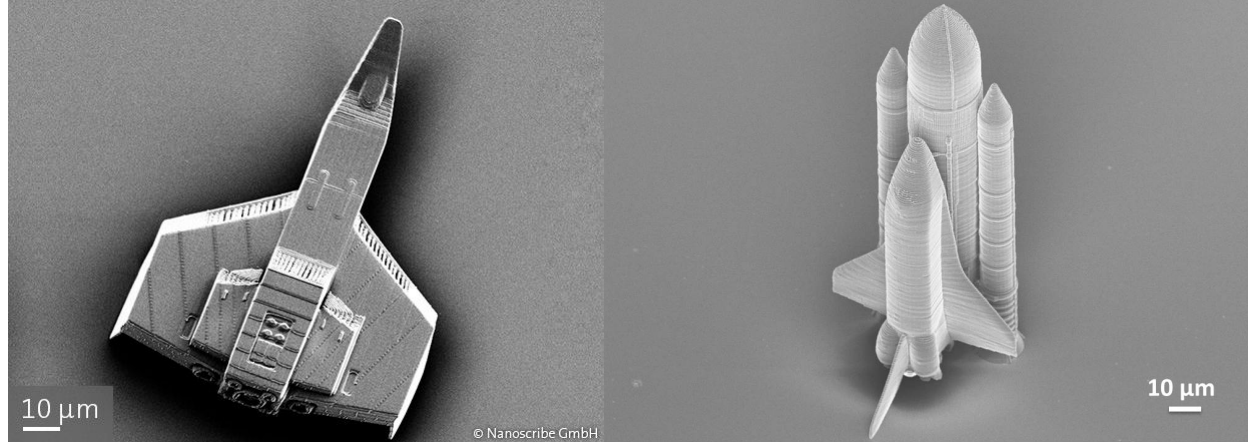
Objective

- The objective of this research is to determine the viability of fabricating bistable MEMS with the Nanoscribe Photonic GT system.
- If viable, this would be much faster and provide more flexibility.

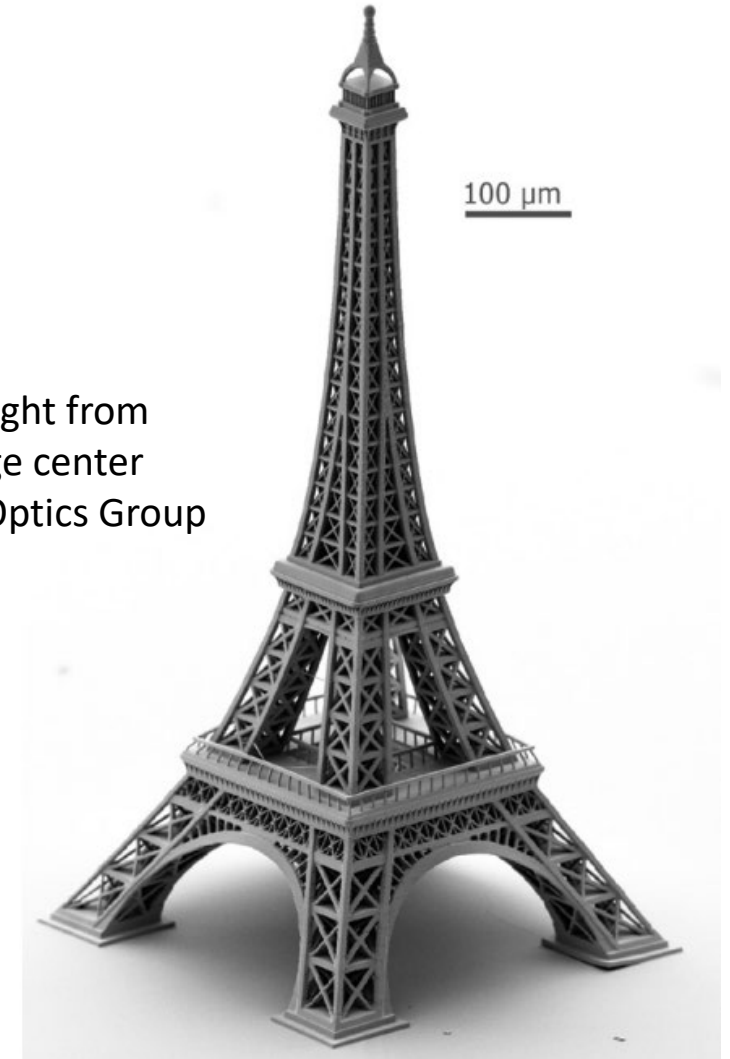


What is the Nanoscribe Tool?

- New 3D printer that utilizes 2 photon polymerization
- 3D feature size of 160nm possible
- Prints on nano, micro, and meso scales
- Compatible with dozens of photoresists



Images left and right from Nanoscribe. Image center from UCF Nano-Optics Group



Materials

- Photoresists
 - IP-S – High viscosity, high strength, high surface quality, fast print rate
 - IP-Dip – Low viscosity, low strength, high level of detail
- Objectives
 - x25 – low level of detail, wide print field
 - x63 – high level of detail, small print field
- Substrates
 - Silicon
 - ITO Glass
 - Glass

Design Strategy

- Materials divided into 3 sets based on manufacturer's recommendations
- 3 Bistable Dome designs explored

	Photoresist	Objective	Substrate
Material set 1	IP-Dip	x63	Glass
Material set 2	IP-S	x25	ITO Glass
Material set 3	IP-S	x25	Silicon

	Design 1	Design 2	Design 3
Material set 1	X		
Material set 2		X	X
Material set 3	X	X	X

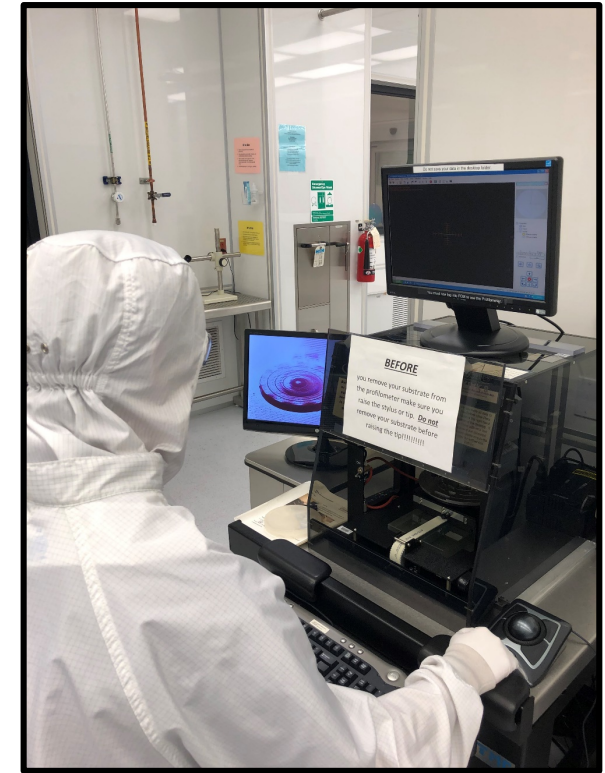
Fabrication Process

- Designed in Solidworks
- Exported to DeScribe
- Parameters for print job set in DeScribe
 - Parameters such as slicing thickness, splitting, laser power and speed, etc.
- Printed
- Developed in PGMEA for 30 minutes, then IPA for 2 minutes



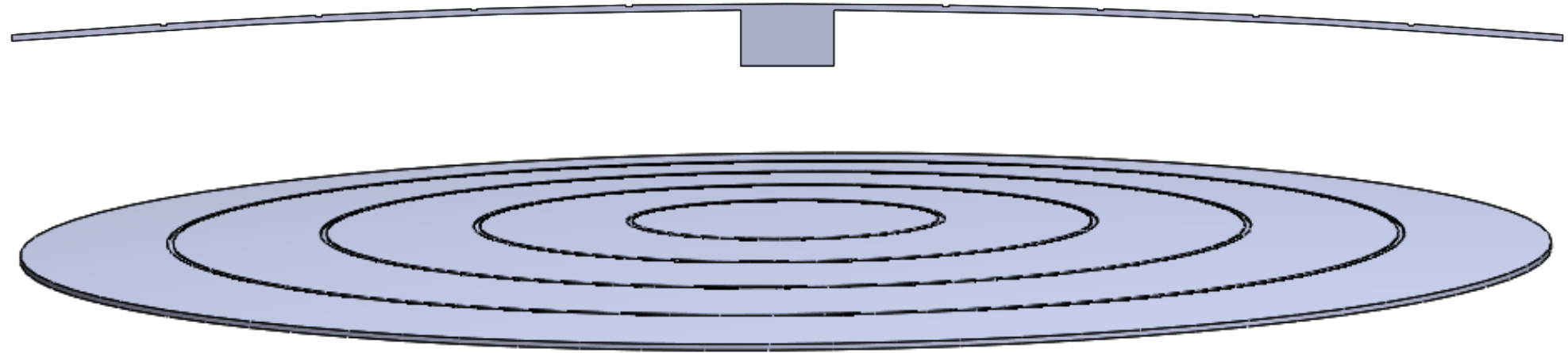
Characterization

- Each design was printed multiple times in multiple sizes
- Designs were modeled (Solidworks) and simulated (Ansys) to prove bistability
- Samples were imaged with optical and scanning electron microscopy
- Samples were characterized with a Dektak profilometer and Zygo image surface profile.



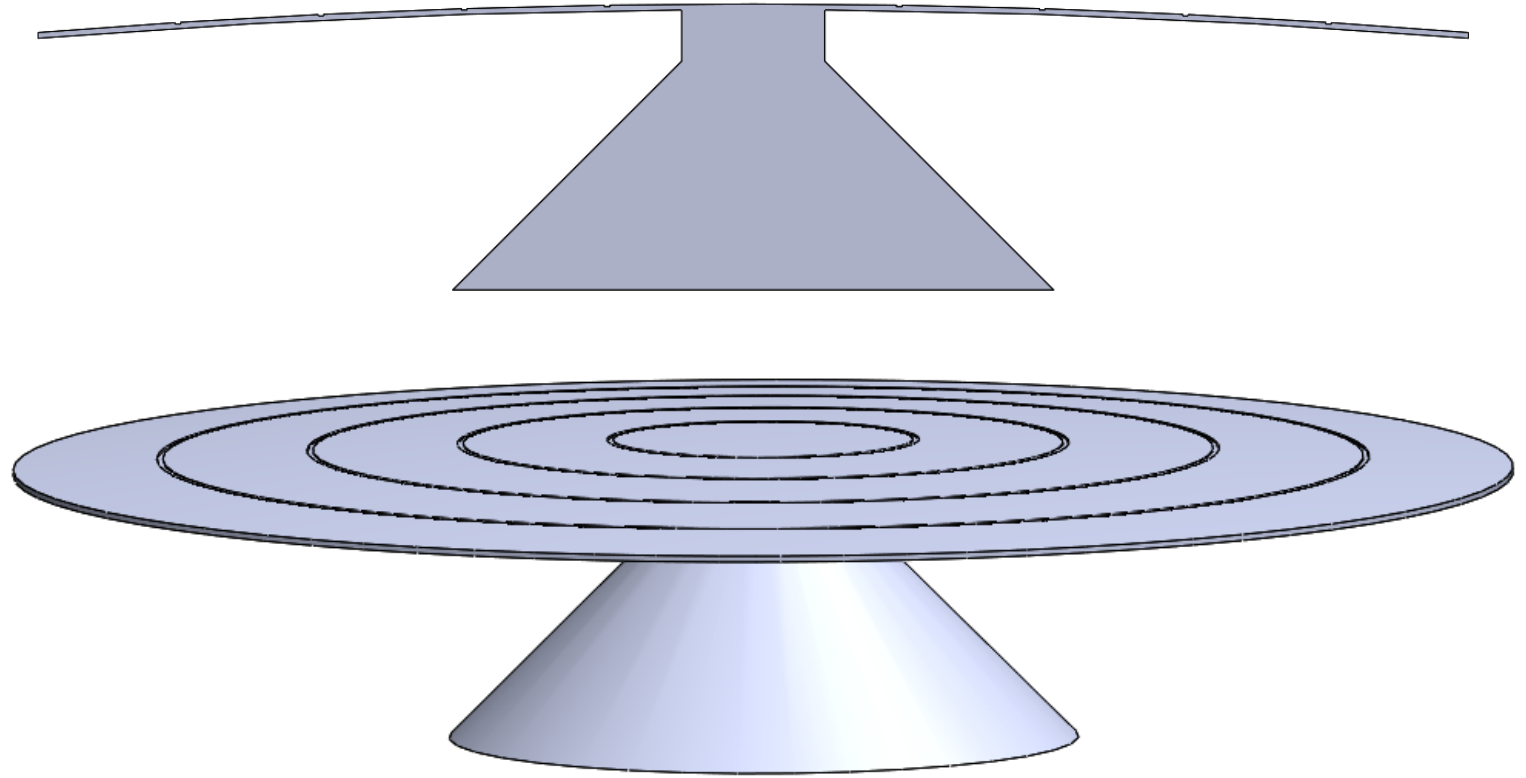
Dome Design 1

- “Mushroom” dome
- Very short anchor
- Simplistic



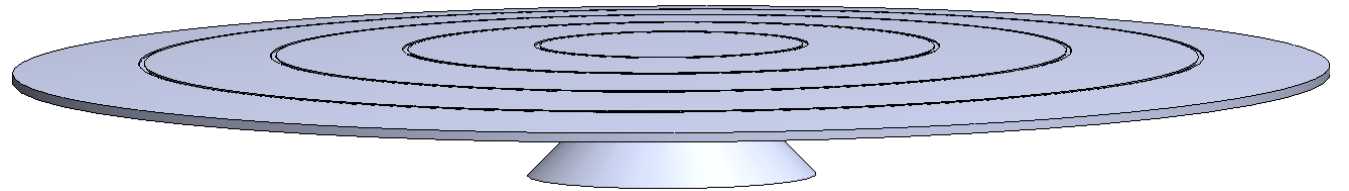
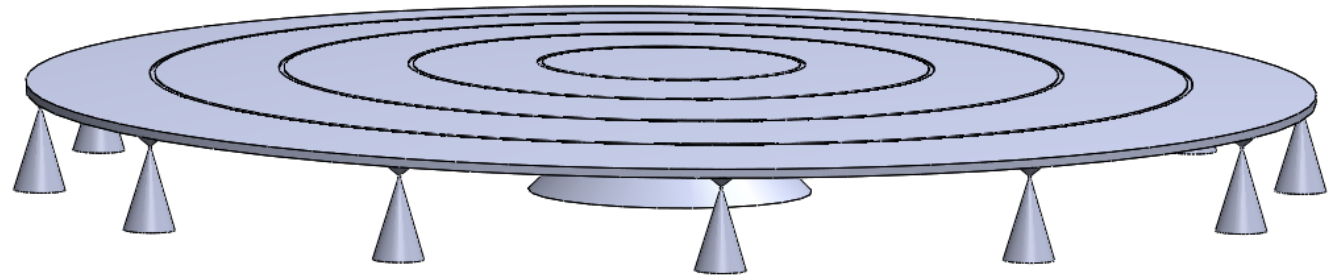
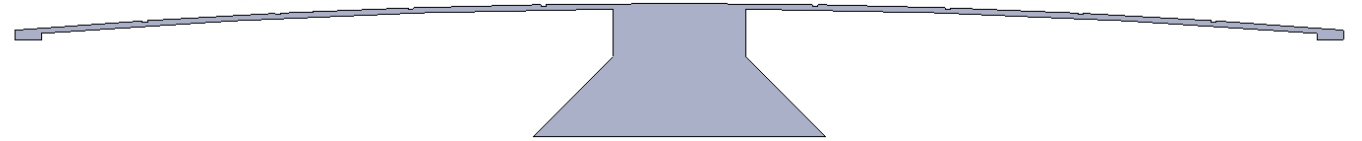
Dome Design 2

- Thicker tapered anchor
- Taller anchor



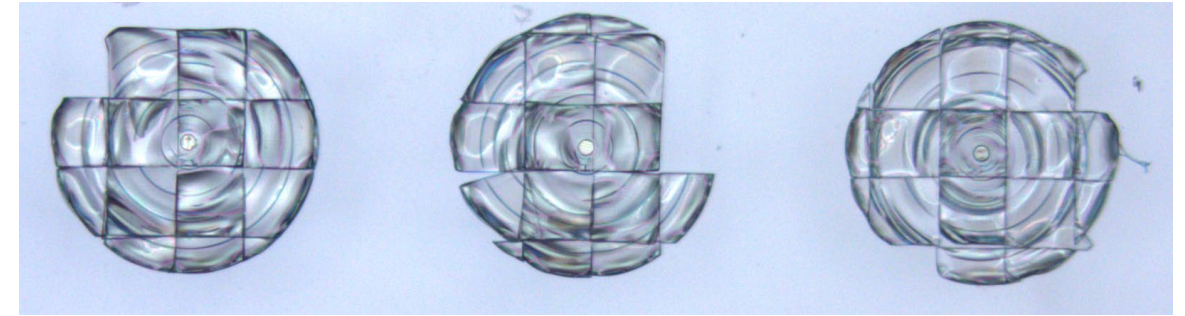
Dome Design 3

- Slightly shorter anchor
- Thicker perimeter
- 2 versions
 - One with periodic supports along the edge of dome (designed to release)
 - One without supports

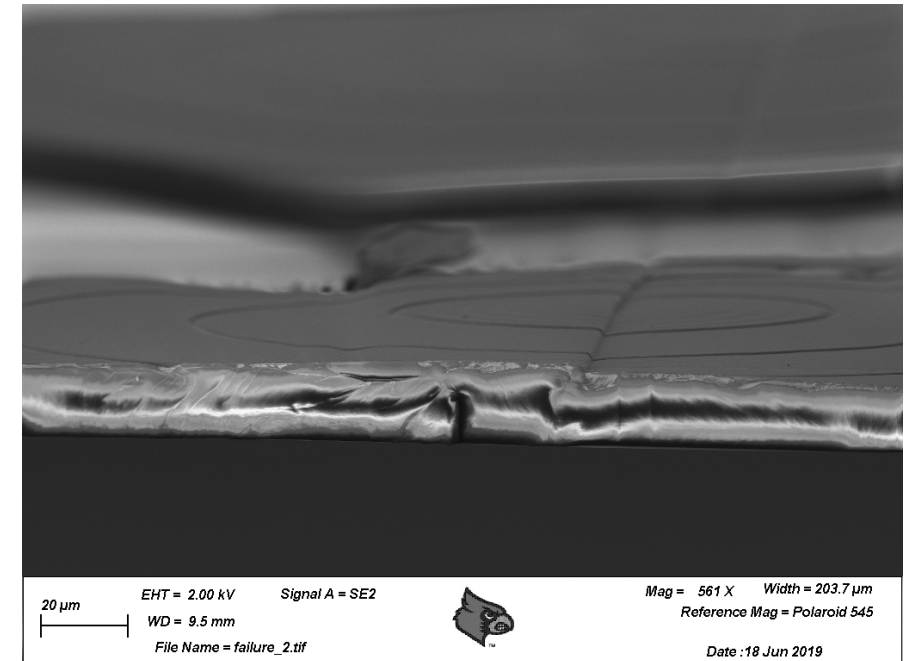


Results

- Design 1
 - Structures made with Material Set 1 warped and collapsed on themselves
 - Material Set 1, with IP-Dip, deemed unsuitable
 - Structures made with Material Set 3 had unpolymerized resist trapped under dome



Above- Structures fabricated using Material Set 1
Below- Cross section of structure fabricated using Material Set 3

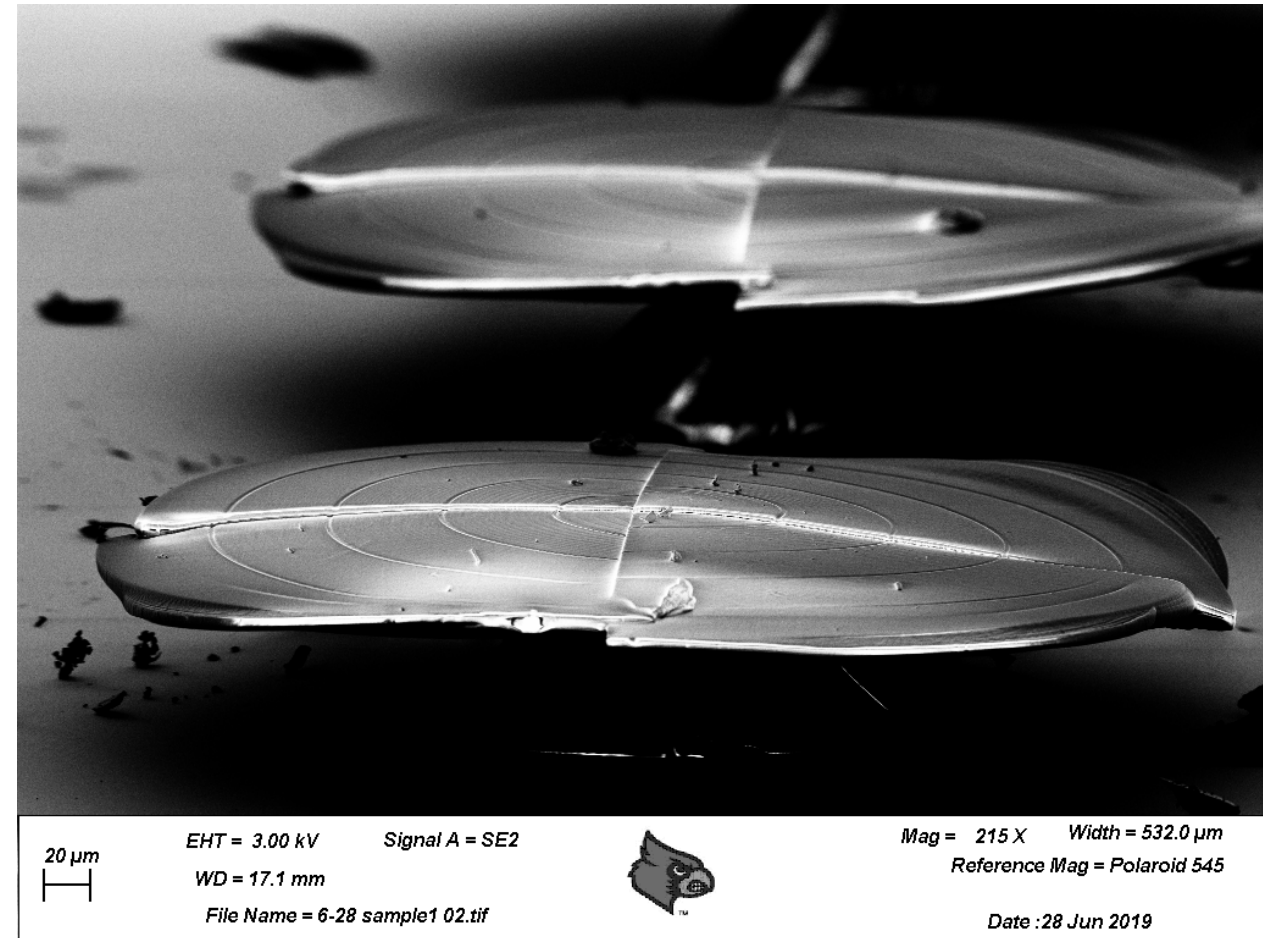


1. Neither Material Set resulted in a successful dome structure.
2. Material Set 1 had severe stitching problems and was ruled out.
3. Material Set 3 remained a possibility if the anchor height is increased.

Results

- Design 2
 - Structures made with Material Sets 2 and 3 both warped and did not align well at the stitching lines
 - Material Set 2 required a lower laser power, which may lead to a weaker structure

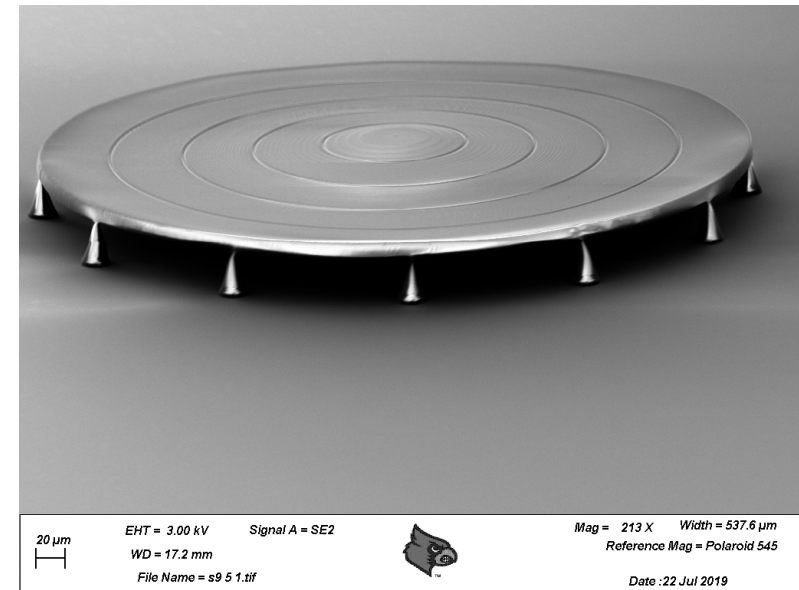
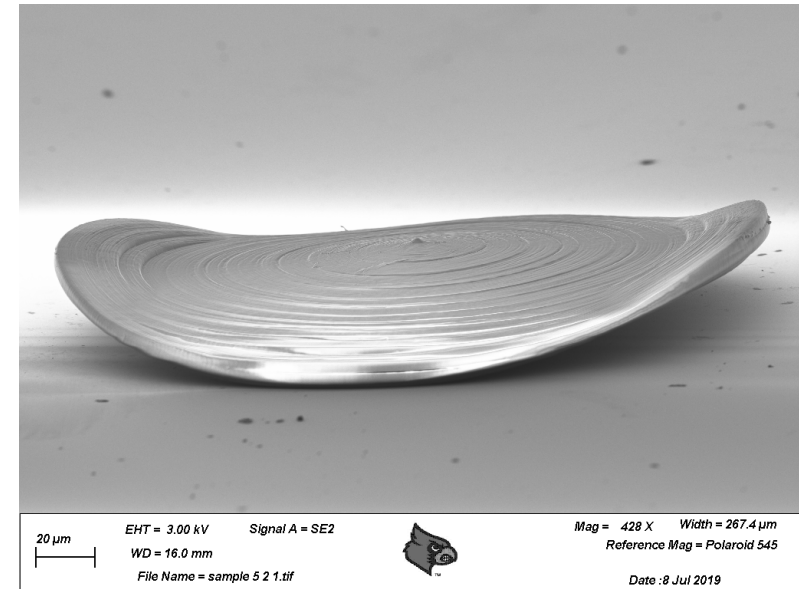
1. Increasing the anchor height resolved the undeveloped resist issue.
2. Both Material Sets produced warped domes.
3. The fabrication of unsupported structures is challenging with the Nanoscribe!



Results

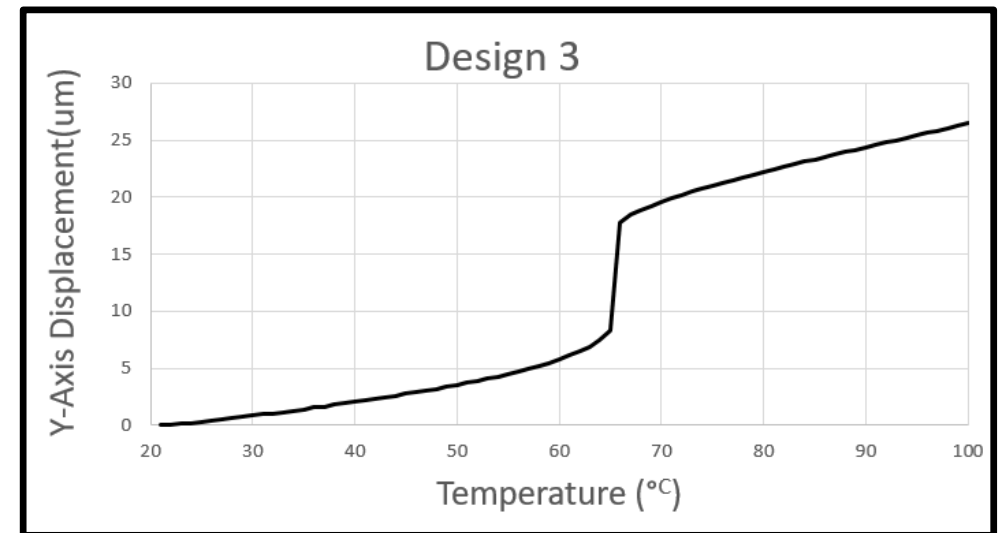
- Design 3
 - Unsupported version
 - Severe warping
 - Supported Version
 - Printed as designed without major defect

1. The unsupported dome design failed as expected, but the supported design was successful, illustrating that edge supports are necessary.
2. More importantly, it proved that these concave-down dome structures could be printed successfully.



Simulation

- Design 3 was simulated with a 1 μ m layer of Aluminum (TCE = 23 ppm/K) covering the top surface of the 2 μ m thick polymer dome (TCE = 70 ppm/K). The simulation shows that as temperature increases, the bilayer concave-down dome abruptly changes states due to the mismatch in the materials' coefficient of thermal expansion, proving bistability.



Conclusions

- The Nanoscribe tool has extreme difficulty fabricating “unsupported thin structures”.
- This can be overcome with strategically-placed support elements.
- The combination of IP-S (the thicker resist), the x25 objective, and a silicon substrate was most suitable for this application.
- Ansys was used to demonstrate that a bilayer dome of polymer-aluminum can exhibit mechanical bistability.
- The Nanoscribe is potentially a viable means of fabricating bistable MEMS structures.

Recommendations

- Continue with the experimentation by coating the successful MEMS domes with aluminum and test for mechanical bistability.

Acknowledgements

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